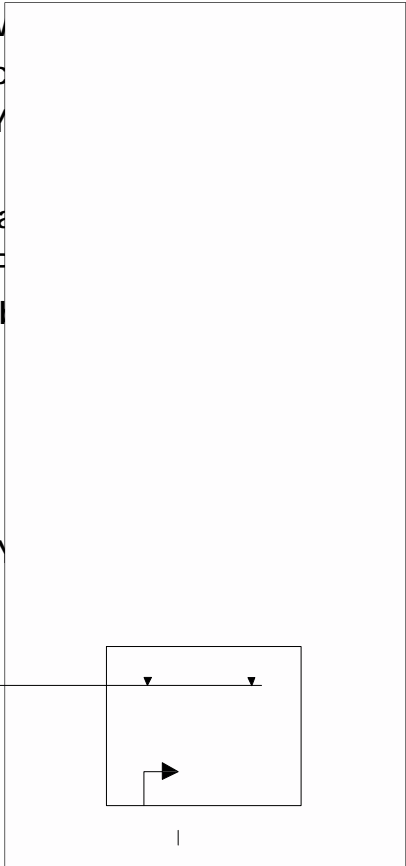




DESCRIPTION:

HOY d f c Xi WPg Mf Y f* Y `dVnbg B H Q] W W V Q] W
Mb 5 ` ; M5 g] b Z f IXf] YcXX Y a]]bP]i bPg PM[Y c
Wc i d ` Y X Pc MO] [O! Qc ` PM[Y c i Pd i PX Y
Wc b g] g Pg c Z MO] [Q `gRMY WX d CXPc Qf f
W] f Wi] Pf mBH OY dXf Yc` Xni iWPy Mf] Yo R]MWWi a
Mi Pc a c P] QY NMPPY f m a Mb M[Y a Y b Pg mg F
Mb X d c RY f g mg PY a] b g i ` MP] c b PY g P] I
9 A F Cf Y Y X f Y ` Mm f Y d ` MWY a Y b PB



BH OY X Y

NMPPY f

Wc b Pf c

MAIN FEATURES:

- <] [O] g cD\$NPS d b a g
- G] b [` Y WOMb b Y ` b c fy d N c ` n c G G b b [Y
- C d Y f MP] b [PYafdMbf[MP] f(\$ š F Pc %%\$ š F
- F 9 5 F < / F c < G Wc a d `] Mb WY
- < 6 A . < ' 5 / A A . A (/ FGA . F
- FE FMd d f c QY X
- J G9 Md d f c QY X
- I IMd d f c QY X

ABSOLUTE MAXIMUM RATINGS fl HY a d Y f MPi f Y 1 & DŠ FŁ

Parameter		Symbol	Value	Unit
Input	For k ard Current	FI	50	mA
	Pea _ For k ard Current	IFP	1 ⁷	\$
	5HYHUVH 9ROWDJH	9 ₅		
	3RZHU 'LVVLSDWLRQ	3'		
2XWSXW	6ZLWFKLQJ 9ROWDJH	2	9	
	&RQWLQXR XV / RDG &X U UHQW			
	3RZHU 'LVVLSDWLRQ	3&		P :
2SHUDWLQJ 7HPSHUDWXUH		7 _{RSU}	a	
-XQFWLRQ 7HPSHUDWXUH		7 _M		
6WRUDJH 7HPSHUDWXUH		7 _{VWJ}	a	
7RWDO 3RZHU 'LVVLSDWLRQ		3 _{WRW}		P :
,VRODWLRQ 9ROWDJH		9 _{LVR}	⁸	9UPV

Solderin [Temperature	T _{sol}	260	
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NOTE1 íî... • %oîµ ò, ì (ŒE < µ v Ç

NOTE2 (}ŒE íu]vµš U ZX, XA ðì • òì9

ELECTRICAL CHARACTERISTICS fl Temperature 1 25 š C Ł

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage [e	V _F	I _F 1 10mA	-	1.2	1.5	V
	Reverse Current	I _R	V _R 1 6V	-	-	1	A
	Terminal Capacitance	C	V 1 0, Z 1 1M < n	-	-	70	pF
	Reset Current	I _{FR OFF Ł}	I _O 1 0 Ĥ R MAL Ł	0.1	-	-	mA
Output	Open-circuit lea _ a [e current	I _{Lea _}	V _O 1				

ORDERING INFORMATION

>] Y>] Y A] Wf cY` Y]W CF A 5 & 5 F ! G* D OG C
] W

Characteristics Curves

FIG.1: Forward Current vs. Forward Voltage [mA]

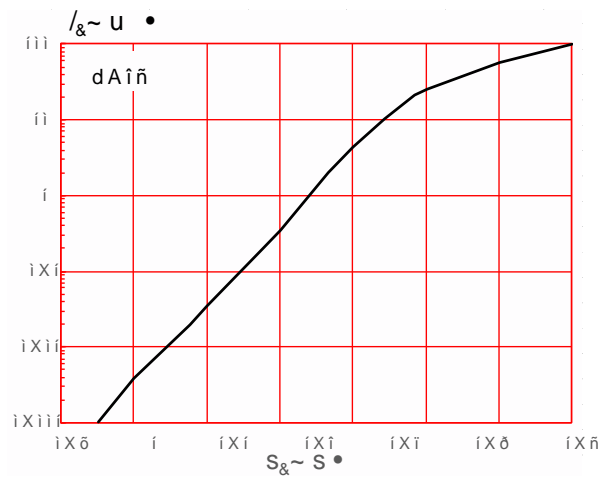


FIG.2: Max. Allowable LED Forward Current vs. Ambient Temperature

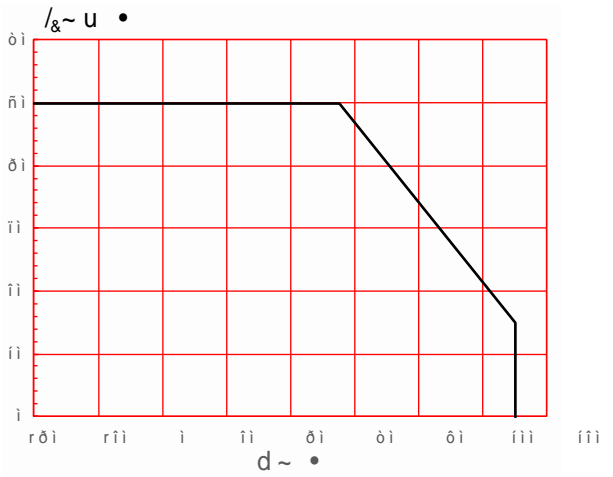


FIG.3: LED Operate Current vs. Ambient Temperature

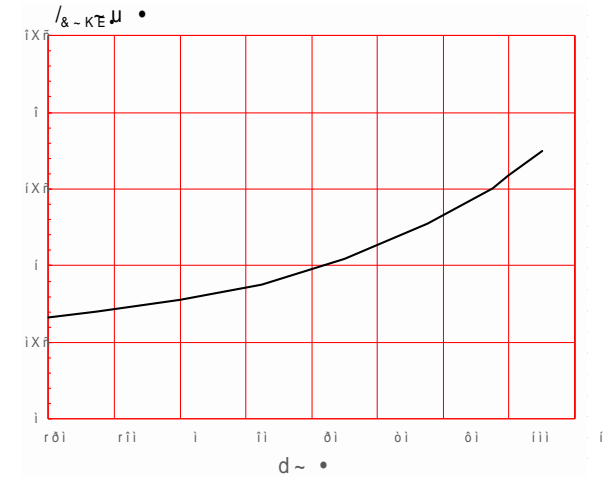


FIG.4: On Resistance vs. Ambient Temperature

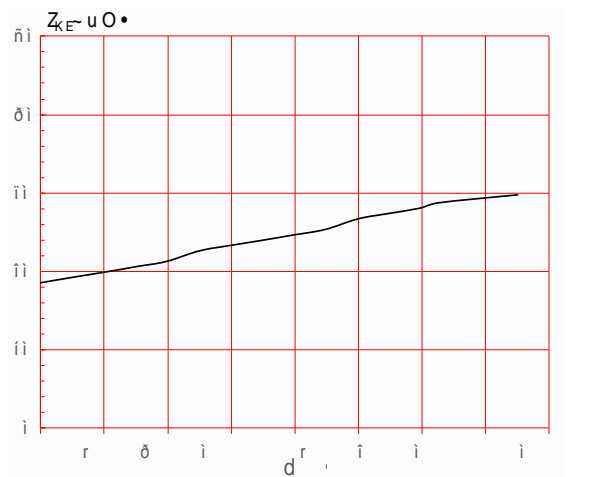


FIG.5: Turn On Time vs. Ambient Temperature

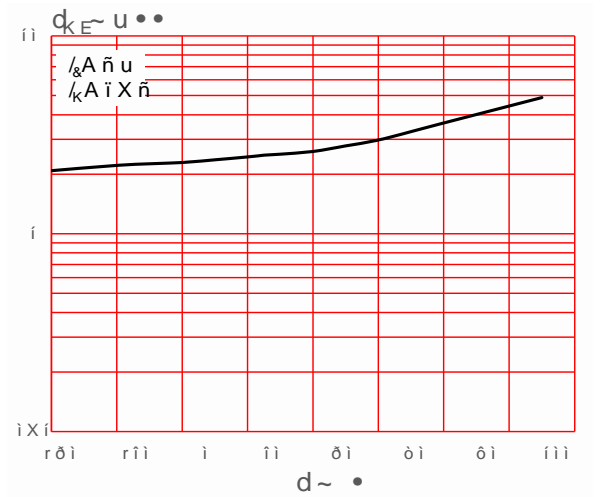
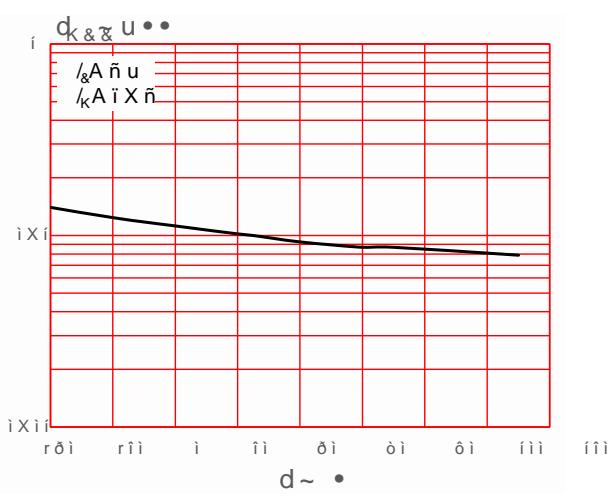
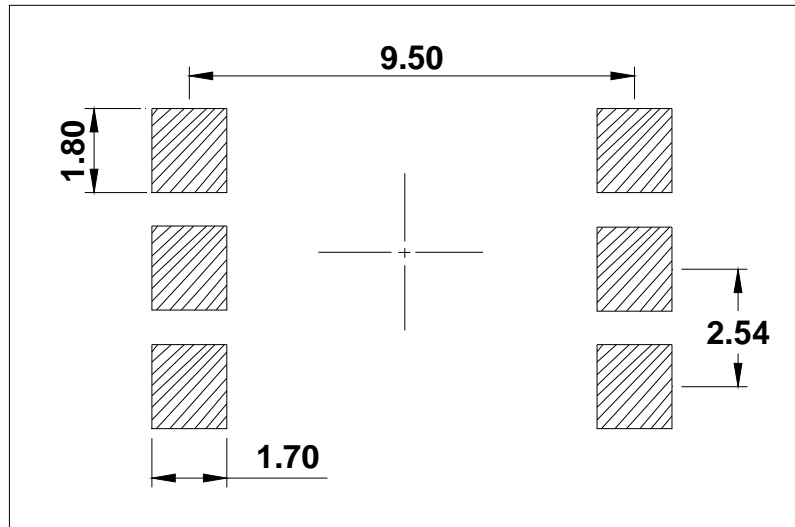


FIG.6: Turn Off Time vs. Ambient Temperature



RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

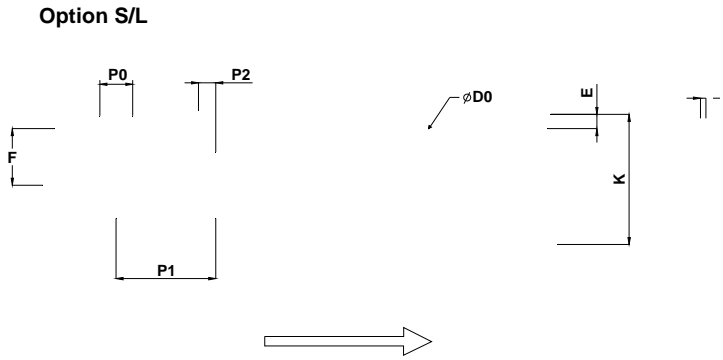
Option SMD



T Q

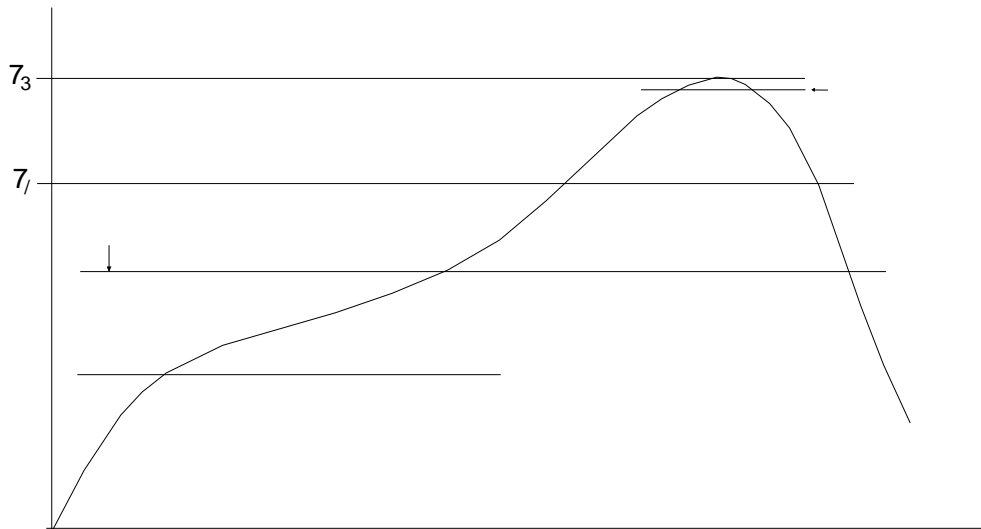
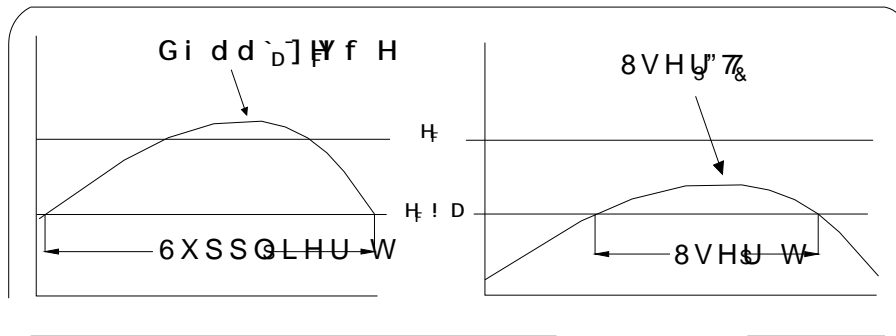
J \$

CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

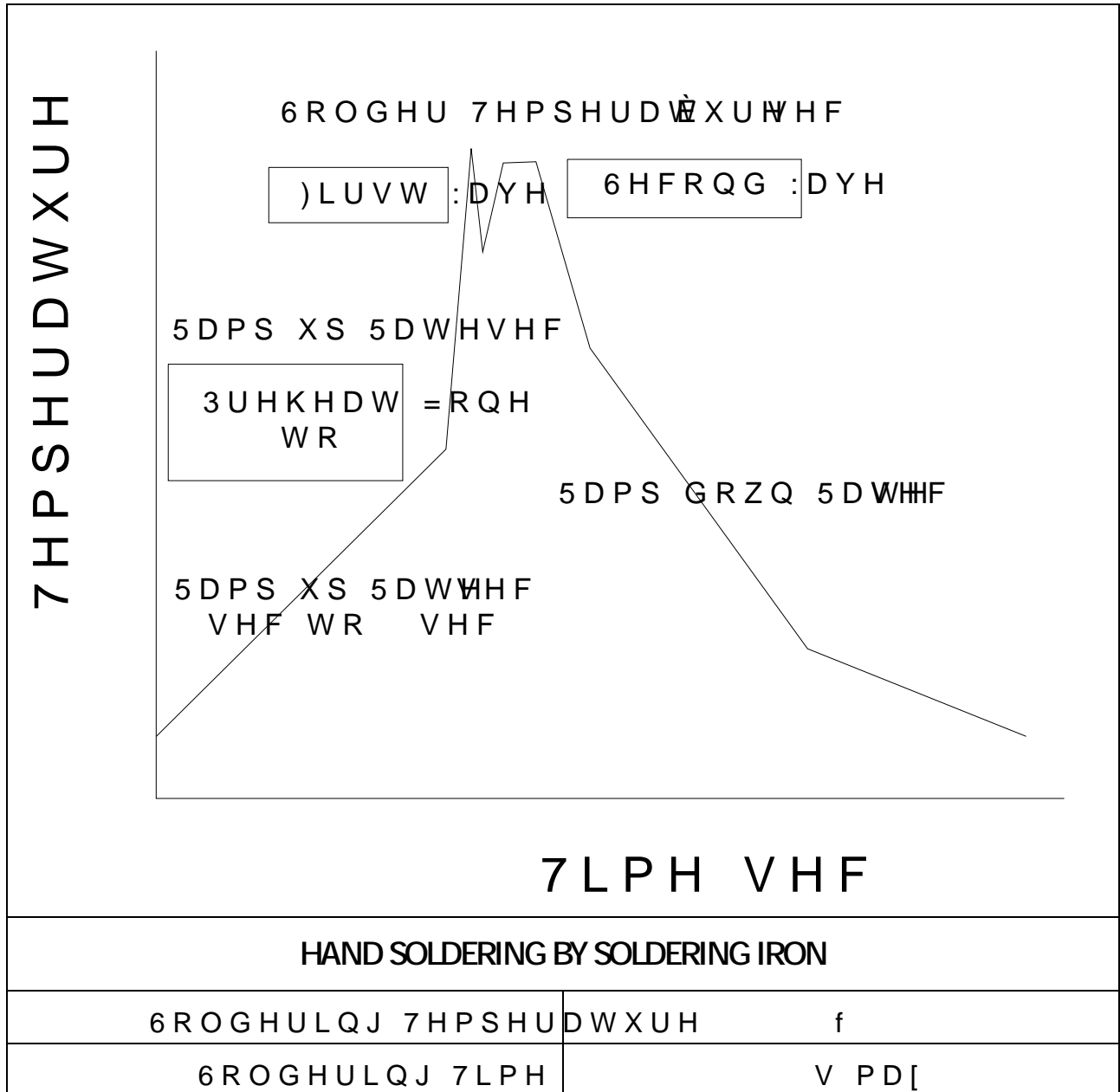


5 HI	'LPHQVLRQV					
	0LOOLPHWUUV ,QFKHV					
	0LQ	7\ S	0D[0LQ	7\ S	0D[
,						
3						
3						
3						
(
)						
7						
:						

REFLOW INFORMATION



WAVE SOLDERING



Note:

1. Re-Zlok soldering [is recommended at t \ e temperatures and time n, no more t \ an t \ ree times.
2. Avoid direct contact bet k eeñ e epoxy body and any tools osur Z aces exceedin [its maximum stora [e temperature.
3. Application o Z pressure dnepoxy body is p \ ibited atlevated temperatures. In speci Z ic scenarios, any applied Z or must not exceed 2.5N.
4. Ensure t \ e component \ as cooled to ambient temperaturee p rcedin [k i any subse e uent manu Z acturin [steps.
5. T \ e component \ as a s \ e Z i Z Z a e fl t